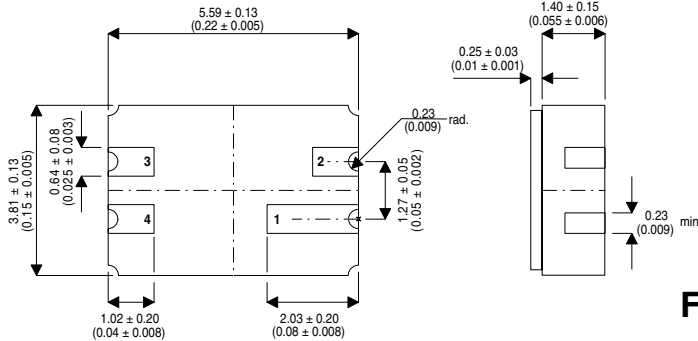


MECHANICAL DATA

Dimensions in mm (inches)



N-CHANNEL ENHANCEMENT MODE MOSFET

V_{DSS} **90V**
 I_D **0.9A**
 $R_{DS(on)}$ **4.0Ω**

FEATURES

- Faster switching
- Low Ciss
- Integral Source-Drain Diode
- High Input Impedance and High Gain

DESCRIPTION

This enhancement-mode (normally-off) vertical DMOS FET is ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

High Reliability Screening options are available.

CERAMIC LCC3 PACKAGE (MO-041BA)

(Underside View)

PAD 1 – DRAIN PAD 3 – SOURCE
 PAD 2 – N/C PAD 4 – GATE

ABSOLUTE MAXIMUM RATINGS $T_{CASE} = 25^{\circ}C$ unless otherwise stated

V_{DS}	Drain - Source Voltage	90V
I_D	Drain Current	0.9A
	- Continuous ($T_C = 25^{\circ}C$)	
	- Continuous ($T_C = 100^{\circ}C$)	0.7A
I_{DM}	Drain Current	3A
	- Pulsed (Note 1)	
V_{GS}	Gate - Source Voltage	$\pm 20V$
$P_{tot(1)}$	Total Power Dissipation at $T_{mb} \leq 25^{\circ}C$	6.25W
	De-rate Linearly above $25^{\circ}C$	0.050W/ $^{\circ}C$
$P_{tot(2)}$	Total Power Dissipation at $T_{amb} \leq 25^{\circ}C$	0.5W
T_j, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150 $^{\circ}C$

THERMAL DATA

R_{thj-mb}	Thermal Resistance Junction – Mounting base	Max	20	$^{\circ}C/W$
$R_{thj-amb}$	Thermal Resistance Junction - Ambient	Max	250	$^{\circ}C/W$

NOTES: 1) Repetitive Rating: Pulse Width limited by maximum junction temperature.
 2) Pulse Test: Pulse Width $\leq 380\mu S$, Duty Cycle, $\delta \leq 2\%$

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STATIC ELECTRICAL RATINGS ($T_{case} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$ Drain – Source Breakdown Voltage	$V_{GS} = 0V$ $I_D = 1.0\mu A$	90	-	-	V
$V_{GS(th)}$ Gate – Source threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 1.0mA$	0.8	-	2	
	$T_C = 125^{\circ}\text{C}$	0.3	-	-	
I_{GSS} Gate – Source Leakage Current	$V_{GS} = \pm 20V$ $V_{DS} = 0V$	-	-	± 100	nA
	$T_C = 125^{\circ}\text{C}$	-	-	± 500	
I_{DSS} Zero Gate Voltage Drain Current	$V_{DS} = 72V$ $V_{GS} = 0V$	-	-	1.0	μA
	$T_C = 125^{\circ}\text{C}$	-	-	100	
$I_{D(on)}$ On – State Drain Current (note 2)	$V_{DS} = 15V$ $V_{GS} = 10V$	1.5	-	-	A
$R_{DS(on)}$ Drain – Source On Resistance (note 3)	$V_{GS} = 5V$ $I_D = 0.3A$	-	-	5.3	Ω
	$V_{GS} = 10V$ $I_D = 1.0A$	-	-	4	
	$T_C = 125^{\circ}\text{C}$	-	-	7.5	
$V_{DS(on)}$ Drain – Source On Voltage (note 2)	$V_{GS} = 5V$ $I_D = 0.3A$	-	-	1.6	V
	$V_{GS} = 10V$ $I_D = 1.0A$	-	-	4	
	$T_C = 125^{\circ}\text{C}$	-	-	7.5	
g_{FS} Forward Transconductance (Note 2)	$V_{DS} = 7.5V$ $I_D = 0.475A$	170	-	-	ms
V_{SD} Diode Forward Voltage (Note 2)	$V_{GS} = 0V$ $I_s = 0.86A$	0.7	-	1.4	V

DYNAMIC CHARACTERISTICS

C_{iss} Input Capacitance	$V_{DS} = 25V$ $f = 1.0MHz$	$V_{GS} = 0V$	-	-	50	pF
C_{oss} Output Capacitance			-	-	40	
C_{rss} Reverse Transfer Capacitance			-	-	10	
$T_{d(on)}$ Turn-On Delay	$V_{DD} = 25V$ $R_{GS} = 50\Omega$	$I_D = 1A$ (Note 2)	-	-	10	ns
$T_{d(off)}$ Turn-Off Delay Time			-	-	10	

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